

## PATENT ASSIGNMENT COVER SHEET

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<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JONG HWI LEE	08/21/2012
MIN KYUNG LEE	08/20/2012
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<b>PROPERTY NUMBERS Total: 1</b>	
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Application Number:	14243627
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<b>DATE SIGNED:</b>	10/01/2014
<b>Total Attachments: 2</b>	
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**ASSIGNMENT**

WHEREAS, the undersigned inventor(s) (referred to, collectively, if more than one, as "Assignor") have made an invention entitled **POLYMER OR POLYMER COMPOSITE MEMBRANE HAVING THROUGH-THICKNESS MICROPORES, AND METHOD FOR PREPARING SAME** for which an application for United States Letters Patent was filed on August 23, 2012 as Application Serial No. 13/580,849, and

WHEREAS **CHUNG-ANG UNIVERSITY INDUSTRY-ACADEMY COOPERATION FOUNDATION**, a Korean University ("Assignee") having a place of business at **221, Heukseok-dong, Dongak-gu, Seoul 156-756, Republic of Korea**, desires to acquire all right, title and interest in and to the above identified invention and application;


NOW, THEREFORE, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, does hereby sell, assign, convey and transfer unto Assignee all right, title and interest in and to the above identified invention and application, together with all corresponding foreign applications and patents which may be filed thereon, including the right to claim priority from the above identified United States application; and Assignor hereby agrees that Assignor will sign all lawful papers, including, without limitation, all divisional, continuation, renewal, extension and reissue applications, and make all rightful oaths in execution thereof, and will generally do everything possible to aid Assignee, its successors, assigns and nominees to obtain and enforce proper protection for the invention in all countries, this obligation to be binding upon Assignor (each and severally, if more than one) and upon Assignor's personal representative or other legal successor.

Assignor hereby authorizes and requests Swanson and Bratschun, L.L.C. to insert herein above the application serial number and filing date of said application when known.

IN TESTIMONY WHEREOF, the undersigned Assignor (and each of them, if more than one) has signed below.

Date: Aug 21, 2012

Address:

  
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Date: August 20, 2012

  
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